

ABSTRACT OF THE DISCLOSURE

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Electrodes of one face of a semiconductor which has electrodes formed to both faces and a heat radiating plate are directly joined to quickly absorb and diffuse heat of the semiconductor, thereby improving a heat radiation effect. At the same time, electrodes are connected with use of a wire thicker than a wire for wire bonding and larger in current capacity and can accordingly be utilized as a connecting terminal to a circuit board. Ceramic is used for the heat radiating plate, so that semiconductors of different functions can be mounted simultaneously.

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